

# Material Composition Specification

D<sup>2</sup>PAK Case

Available with Pb(lead)-free plating\*



Device average mass ..... 1468 mg  
Fluctuation margin ..... +/-10%

Device part	Substance	mass (mg)
active device	doped Si	3.13
leadframe	Cu Alloy	868
die attach	Pb92.5Ag2.5Sn5	23.1
*plating	SnPb10	12.5
	or Sn (100% tin, Pb-free)	12.5
encapsulation	epoxy molding compound -silica 70% -epoxy 20% -phenol resin 10% -Sb <sub>2</sub> O <sub>3</sub> < 1.0%	561
<b>Packing material (per 13" reel)</b>		<b>(g)</b>
reel	polystyrene	308
carrier tape	polycarbonate	118
cover tape	polyester	17
box	cardboard	272
bubble wrap	polyethylene, ethoxylated fatty amine	34
label/tape	paper	22

\*Specify Lead-free when ordering 100% tin (Pb-free) plating option.